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**DRAFT AGENDA – OPEN SESSION
FY23 BOARD OF GOVERNORS MEETING
Tuesday, October 4, 2022 – 3:30 pm to 4:00 pm (EDT)**

1. Opening of the Meeting (Start Time 3:30 pm)

- 1.1. Call to Order
Karen Ohland
- 1.2. Adoption of the Agenda ACTION
- 1.3. President’s Remarks (10 minutes) INFORMATION
Karen Ohland
- 1.4. Executive Director/CEO’s Remarks (10 minutes) INFORMATION
Tom Costabile
- 1.5. Consent Items for Action ACTION

Identification of items to be removed from Consent Agenda

Consent Items for Action are items the Board is asked to take action on as a group. Governors are encouraged to contact ASME Headquarters with their questions prior to the meeting as it is not expected that consent items be removed from the agenda.

- 1.5.1. Approval of Minutes from June 19, 2022 and June 21, 2022 Meetings
- 1.5.2. Proposed Appointments
- 1.5.3. New Society Level Award – ASME Avram Bar-Cohen Memorial Award

2. Open Session Agenda Items

- 2.1. FY23 YTD Financial Report (10 minutes) INFORMATION
Bill Garofalo

3. New Business

4. Open Session Information Items

- 4.1. Dates of Future Meeting

DATE	DAY	TIME	LOCATION
October 30, 2022	Sunday	8:30 am – 3:00 pm	Columbus, OH
November 11, 2022	Friday	2:00 pm – 3:30 pm	Virtual (Information Session)
December 5, 2022	Monday	2:00 pm – 3:30 pm	Virtual (Information Session)
January 31, 2023	Tuesday	12:00 pm – 2:00 pm	Virtual
March 6, 2023	Monday	2:00 pm – 2:30 pm	Virtual (Information Session)

April 19, 2023	Wednesday	12:00 pm – 2:30 pm	Virtual
May 5, 2023	Friday	2:00 pm – 3:30 pm	Virtual (Information Session)
June 4, 2023	Sunday	8:30 am – 3:00 pm	St. Louis, MO
June 6, 2023*	Tuesday	8:30 am – 3:00 pm	St. Louis, MO

*FY24 Board of Governors

5. Adjournment of Open Session

List of Appendices

1.5.2 Proposed Appointments

1.5.3 New Society Level Award – ASME Avram Bar-Cohen Memorial Award

**ASME Board of Governors
Agenda Item
Cover Memo**

**Date Submitted: September 6, 2022
BOG Meeting Date: October 4, 2022**

**To: Board of Governors
From: Committee on Organization and Rules
Presented by: Emily Boyd
Agenda Title: Proposed Appointments**

Agenda Item Executive Summary:

Proposed appointments reviewed by the COR on September 6, 2022.

Proposed motion for BOG Action:

To approve the attached appointments.

Attachments: Document attached.

OCTOBER 2022 PROPOSED APPOINTMENTS TO ASME UNITS

Internal Unit	Nominee	Appointment Position/Title	Appointment Term/Category	Appointment Type	History
Committee on Finance	Adam Hamilton	Member-at-Large	October 2022 – June 2025	Initial	Member, Industry Advisory Board
Committee on Finance	Amip Shah	Member-at-Large	October 2022 – June 2024	Initial	Executive Director Recruitment Committee; Member, Nominating Committee; E-Fest Steering Committee
Committee on Honors	Nancy Johnson	Member-at-Large	October 2022 – June 2025	Initial	Past Chair, Aerospace Division; Past member of Spirit of St Louis Medal Committee, Recipient of ASME Adaptive Structures and Materials Systems Award
Committee on Honors	Pamela Norris	Member-at-Large	October 2022 – June 2025	Initial	Associate Editor of the ASME Journal of Heat Transfer; 2021 Honorary Member
Committee on Honors	Leslie Phinney	Member-at-Large	October 2022 – June 2025	Initial	Member, Diversity, Equity and Inclusion Strategy Committee; Member, J&J Medal Committee
Member Development and Engagement Sector	Ying Feng Pang	Member-at-Large	July 2022 – June 2023	Reappointment	Current member of MDE Sector Council; Past Chair of ASME Santa Clara Valley Section
Public Affairs and Outreach Sector	Keyanna Conner	Member-at-Large	October 2022 – June 2023	Initial	Former consultant to ASME, extensive government experience
Philanthropy Committee	Thomas Pestorius	Member-at-Large	July 2022 – June 2025	Reappointment	Past Governor, Past Secretary/Treasurer, Past Senior Vice President
Philanthropy Committee	K. Keith Roe	Member-at-Large	July 2022 – June 2025	Reappointment	Past President; Past Chair, ASME Foundation
Philanthropy Committee	Terry Shoup	Member-at-Large	July 2022 – June 2025	Reappointment	Past President, Past Senior Vice President, Past Vice President

**ASME Board of Governors
Agenda Item
Cover Memo**

Date Submitted: August 2, 2022

BOG Meeting Date: October 4, 2022

To: Board of Governors

From: Committee on Honors

Presented by: Leila Persaud

Agenda Title: New Society Level Award

Agenda Item Executive Summary: *(Do not exceed the space provided)*

The Committee on Honors at its April 29, 2021, meeting approved the elevation the InterPACK Achievement Award to the society-level and to rename it the ASME Avram Bar-Cohen Memorial Award, pending sufficient funding. Subsequent to that meeting the funding needed was secured.

Proposed motion for BOG Action:

To accept the Committee on Honors recommendation to elevate the InterPACK Achievement Award to the society-level and rename it the ASME Avram Bar-Cohen Memorial Award.

Attachment: Yes

PROPOSED ASME AVRAM BAR-COHEN MEMORIAL MEDAL

DESCRIPTION OF AWARD

1. Salutation & Introduction

This proposal is to rename the InterPACK Achievement Award for Professor Avram Bar-Cohen who passed away on October 10, 2020. The goal is to elevate this award to society-level and rename it the “Avram Bar-Cohen Memorial Medal.” This award is sponsored by the Electronics and Photonics Packaging Division and is proposed under ASME policy P-3.2. This award will honor the legacy of Professor Avram Bar-Cohen, in particular his interdisciplinary contributions to the academic and industrial communities in the broad field of heat transfer and related electronics, photonics, mechanics and packaging phenomena.

2. Background

Professor Avram Bar-Cohen had a most distinguished service career, creating the Mechanical Engineering program at Ben Gurion University of the Negev, and serving as Director of the Center for the Development of Technological Leadership at the University of Minnesota, Chair and Distinguished Professor of Mechanical Engineering at the University of Maryland, Manager of the Microsystems Technology Office at the Defense Advanced Research Projects Agency (DARPA) and Principal Engineering Fellow at Raytheon. He truly impacted a vast section of our community in his role as the DARPA Technology Manager and in other positions. His publications, lectures, short courses, and research, as well as his US government and professional service in technical societies, have been vital for the creation of the scientific foundation for the thermal management of electronic components and systems.

Avi Bar-Cohen was the founder and major driving force of the two most prestigious conferences in our fields of thermal management of electronic cooling and packaging of electronics, IEEE ITherm founded in 1988 and ASME InterPACK founded in 1995. He was our tireless advocate for industry-academia collaborations with a rare ability to articulate scientific and technical relevance appreciated by both academicians and practitioners. He was always a maverick, pushing new areas so the thermal community will be involved from the onset of the design process. More recently, he spearheaded the thermal role in co-design and heterogeneous integration. **It is not an exaggeration to claim that he single-handedly elevated the field of electronics packaging into a highly respected and sought-after discipline.**

He was awarded the highest honors in his field, including the top awards from ASME (Edwin Church Medal, Worcester Reed Warner Medal, Electronic and Photonic Packaging Division (EPPD) InterPACK Achievement Award and EPPD Thermal Management Award – now ASME Allan Kraus Medal), from IEEE (Electronics Packaging Field Award, CPMT Outstanding Sustained Technical Contributions Award, and ITherm Achievement Award), from Semi-Therm (Thermi Award), and from the International Centre for Heat and Mass Transfer (Luikov Medal). He also received top recognition from ASME (Honorary Member) and IEEE (Life Fellow).

Dr. Bar-Cohen served his technical societies with great distinction, including on numerous ASME committees, on the Board of Governors of the IEEE CPMT Society, as its President, as past President of the Assembly of International Heat Transfer Conferences, and he served as the Editor-in-Chief of IEEE CPMT Transactions for 10 years.

His passion for and excellence in education, research and practice, his eminent achievements, his devoted service, his personal kindness, his extraordinary technical vision and distinguished leadership, were an inspiration to all of us in the thermal management and packaging communities. Avi was kind with always a wonderful smile and a mentor to so many. His boundless generosity extended to the new generation of leaders by providing guidance on aspects such as conference organization and supporting nominations for individuals in a variety of Society-level roles and recognitions.

3. InterPACK Achievement Award

The InterPACK Achievement Award, established as a division award in 1999, is given to an individual once every year at the ASME InterPACK Conference. The current criteria for that award are as follows:

Candidates should have demonstrated excellence and international recognition in the area of research and development related to electronic packaging, as well as service to the technical community at large. The scientific and technical leadership is demonstrated by the refereed publications (quality and number), patents awarded, products developed, and students advised. Candidates must also have a demonstrated leadership role in InterPACK over the years, such as organizational leadership, track leadership, session chairing, paper presentations and reviews, and so forth. As a general guideline, scientific and technical contributions count for two-thirds of the evaluation score and service counts to one-third of the score.

The intent is to change this criterion slightly, as seen below, with the elevation to society-level status.

3. Name of Award

Avram Bar-Cohen Memorial Medal

4. Description of the Award

The Avram Bar-Cohen Memorial Medal will honor the legacy of Professor Avram Bar-Cohen, in particular his interdisciplinary contributions to the academic, research and industrial communities in the broad field of heat transfer and related electronics, photonics, mechanics and packaging phenomena.

It is expected that awardees will represent the interdisciplinary nature of the field with work that covers multiple aspects and intersections within the field including multiphysics systems co-design with materials, reliability, sustainability, electrical, thermal, mechanics, photonics and/or fluids and packaging considerations; and in their commitment to advancing the field through mentorship and visionary leadership.

The nominee should have seminal contributions in the successful design, development and evaluation of electronics packaging systems demonstrated by leading-edge product development, seminal peer-reviewed papers, filed patents, mentorship and/or leadership of research and development programs.

Nominees must also have demonstrated both visionary leadership and a widespread mentorship role in promoting and supporting the next generation of practitioners.

It is anticipated that the winner of the Avram Bar-Cohen Memorial Medal will be recognized with a \$2000 honorarium, vermeil medal, certificate, and travel expenses in accordance with

the Committee on Honors policy, to the InterPACK conference, to accept the award. The award will be funded through an endowment of \$75,000 plus \$6000 in first year expenses. We have approval from ASME to begin fundraising in partnership with ASME from Avi's friends and colleagues, and his family is preparing an initial gift.

5. Need for such an Award

Despite the fact that our division is named the Electronic and Photonic Packaging Division, there is no major award that recognizes accomplishments in this field. Advances in electronics packaging are fundamental to advancements in electronics and end up impacting all of us who interact with electronics each and every day.

The most similar award is the society-level Allan Kraus Thermal Management Medal. This award recognizes an individual who has demonstrated outstanding achievements in thermal management of electronic systems and his or her commitment to the field of thermal science and engineering. This award recognizes only a subset of our community, leaving out accomplishments in materials, reliability, sustainability, electrical, mechanics, photonics, fluids and packaging considerations. A society-level award in the comprehensive, interdisciplinary field of electronics packaging is long overdue.

6. Financial Provisions

Contingent on the Committee on Honors approval, the award will be funded through an endowment of \$75,000 plus \$6,000 in first-year expenses. We have approval from ASME to begin fundraising in partnership with ASME from Avi's friends and colleagues, and his family is preparing an initial gift. An administrative fee will be periodically reviewed and determined by the Board of Directors of the ASME Foundation, not to exceed 5% of net asset value.

ASME AVRAM BAR-COHEN MEMORIAL MEDAL RULES OF AWARD

Form of Award

A \$2,000 honorarium, a vermeil medal, a certificate, and travel expenses to attend the award presentation in accordance with, the Committee on Honors policy, subject to availability of funds.

Achievement Recognized

The Avram Bar-Cohen Memorial Medal recognizes contributions to academic, research, and industrial communities in the broad field of heat transfer and related electronics, photonics, mechanics and packaging phenomena.

It is expected that awardees will represent the interdisciplinary nature of the field with work that covers multiple aspects and intersections within the field including multiphysics systems co-design with materials, reliability, sustainability, electrical, thermal, mechanics, photonics and/or fluids and packaging considerations; and in their commitment to advancing the field through mentorship and visionary leadership.

The nominee should have seminal contributions in the successful design, development and evaluation of electronics packaging systems demonstrated by leading-edge product development, seminal peer-reviewed papers, filed patents, mentorship and/or leadership of research and development programs.

Nominees must also have demonstrated both visionary leadership and a widespread mentorship role in promoting and supporting the next generation of practitioners.

Limitations

Previous winners of the InterPACK Achievement Award will not be eligible for this award.

Nominations

Nominations will be solicited broadly from the EPPD community. Nominations will be accepted from any individual who has submitted a completed nomination package.

Avram Bar-Cohen Memorial Medal Committee Composition

The Avram Bar-Cohen Memorial Medal will be administered by a six-member selection committee appointed by the Committee on Honors upon the recommendation of the EPPD. The EPPD shall appoint one member of the committee to act as chair. Each member will serve a term of three years, commencing on July 1 and concluding on June 30. Terms will be staggered for continuity, so that all members' terms will not expire at the same time. Members may not serve more than two consecutive terms. It is preferred that academia/government and industry be represented equally on the committee.

Members of the Avram Bar-Cohen Memorial Medal Committee shall refrain from nominating or writing support letters. Members of the Medal Committee are not eligible to receive the award during their time of service.

Review Process

The selection committee will review all submitted nominations with respect to the award criteria, with consideration not only for technical achievement but also for demonstrated

leadership and mentorship roles in the advancing the field. A majority vote is required to select individual(s) for honor.

The chair of the Avram Bar-Cohen Memorial Medal Committee will then recommend the selected nominee to the Committee on Honors by March 1 for consideration of the award.

Nomination Deadlines

February 1: submission to the Avram Bar-Cohen Memorial Medal Committee

March 1: submission of recommendation to the Committee on Honors

Funding

Temporary Restricted: \$ 6,000

Permanently restricted: \$75,000

APPENDIX

Bullet List of similar awards:

- Current InterPACK Achievement Award which will be replaced by the Avram Bar-Cohen Memorial Medal in Electronics Packaging.
- Allan Kraus Thermal Management Medal



Board of Governors Meeting Agenda Item Cover Memo

Date Submitted:	September 6, 2022
BOG Meeting Date:	October 4, 2022
To:	Board of Governors
From:	William Garofalo, Chief Financial Officer
Presented by:	William Garofalo
Agenda Title:	FY23 YTD Financial Report

Agenda Item Executive Summary:

A year-to-date financial report will be provided.

Proposed motion for BOG Action:

None

Attachment(s):

None